

SN74LVC1G126 Single Bus Buffer Gate With 3-State Output

1 Features

- Available in the Texas Instruments NanoFree™ Package
- Supports 5-V V_{CC} Operation
- Inputs Accept Voltages to 5.5 V
- Provides Down Translation to V_{CC}
- Max t_{pd} of 3.7 ns at 3.3 V
- Low Power Consumption, 10- μ A Max I_{CC}
- ± 24 -mA Output Drive at 3.3 V
- I_{off} Supports Live Insertion, Partial-Power-Down Mode, and Back Drive Protection
- Latch-Up Performance Exceeds 100 mA Per JESD 78, Class II
- ESD Protection Exceeds JESD 22
 - 2000-V Human-Body Model
 - 200-V Machine Model
 - 1000-V Charged-Device Model

2 Applications

- Cable Modem Termination Systems
- High-Speed Data Acquisition and Generation
- Military: Radars and Sonars
- Motor Controls: High-Voltage
- Power Line Communication Modems
- SSDs: Internal or External
- Video Broadcasting and Infrastructure: Scalable Platforms
- Video Broadcasting: IP-Based Multi-Format Transcoders
- Video Communication Systems

3 Description

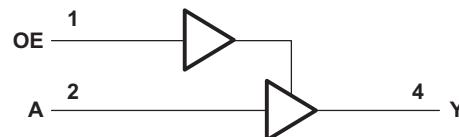
This single buffer is designed for 1.65-V to 3.6-V V_{CC} operation. The LVC1G126 device is a single line driver with 3-state output. The output is disabled when the output-enable input is low.

Device Information⁽¹⁾

| PART NUMBER | PACKAGE (PIN) | BODY SIZE |
|--------------|---------------|-------------------|
| SN74LVC1G126 | SOT-23 (5) | 2.90 mm x 1.60 mm |
| | SC70 (5) | 2.00 mm x 1.25 mm |
| | SOT (5) | 1.60 mm x 1.20 mm |
| | SON (6) | 1.00 mm x 1.00 mm |
| | XBGA (5) | 1.40 mm x 0.90 mm |

(1) For all available packages, see the orderable addendum at the end of the data sheet.

4 Simplified Schematic



An IMPORTANT NOTICE at the end of this data sheet addresses availability, warranty, changes, use in safety-critical applications, intellectual property matters and other important disclaimers. PRODUCTION DATA.

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5 Revision History

Changes from Revision Q (December 2013) to Revision R

| | Page |
|---|------|
| • Added <i>Applications</i> , <i>Device Information</i> table, <i>Handling Ratings</i> table, <i>Feature Description</i> section, <i>Device Functional Modes</i> , <i>Application and Implementation</i> section, <i>Power Supply Recommendations</i> section, <i>Layout</i> section, <i>Device and Documentation Support</i> section, and <i>Mechanical, Packaging, and Orderable Information</i> section..... | 1 |

Changes from Revision P (November 2012) to Revision Q

| | Page |
|--|------|
| • Updated document to new TI data sheet format..... | 1 |
| • Changed MAX operating temperature to 125°C in <i>Recommended Operating Conditions</i> table..... | 5 |
| • Added ESD warning..... | 13 |

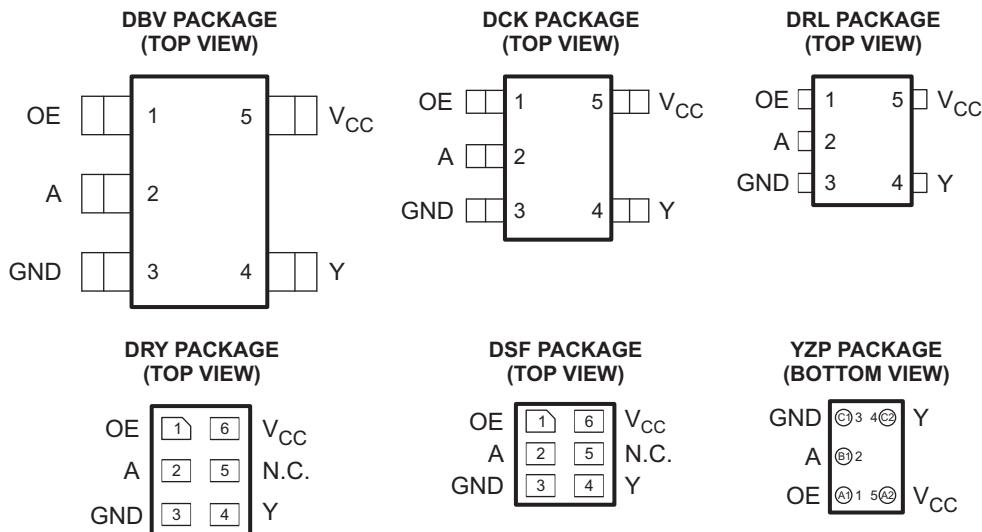
Changes from Revision O (March 2011) to Revision P

| | Page |
|---|------|
| • Removed Ordering Information table..... | 1 |

Changes from Revision N (February 2007) to Revision O

| | Page |
|---|------|
| • Added DSF package option to the data sheet..... | 3 |

6 Pin Configuration and Functions



See mechanical drawings for dimensions.

Pin Functions

| NAME | PIN | | TYPE | DESCRIPTION | | |
|-----------------|-----------------------|----------|------|-----------------|--|--|
| | SN74LVC1G126 | | | | | |
| | DBV, DCK, DRL, YZP | DRY, DSF | | | | |
| A | 2 | 2 | I | A Input | | |
| GND | 3 | 3 | — | Ground Pin | | |
| NC | — | 5 | — | Do not connect | | |
| OE | 1 | 1 | I | OE Enable/Input | | |
| V _{CC} | 5 | 6 | — | Power Pin | | |
| Y | 4 | 4 | O | Y Output | | |

7 Specifications

7.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted)⁽¹⁾

| | | MIN | MAX | UNIT |
|-----------|---|-----------|----------------|------|
| V_{CC} | Supply voltage range | -0.5 | 6.5 | V |
| V_I | Input voltage range ⁽²⁾ | -0.5 | 6.5 | V |
| V_O | Voltage range applied to any output in the high-impedance or power-off state ⁽²⁾ | -0.5 | 6.5 | V |
| V_O | Voltage range applied to any output in the high or low state ⁽²⁾⁽³⁾ | -0.5 | $V_{CC} + 0.5$ | V |
| I_{IK} | Input clamp current | $V_I < 0$ | -50 | mA |
| I_{OK} | Output clamp current | $V_O < 0$ | -50 | mA |
| I_O | Continuous output current | | ± 50 | mA |
| | Continuous current through V_{CC} or GND | | ± 100 | mA |
| T_{stg} | Storage temperature range | -65 | 150 | °C |

- (1) Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under *Recommended Operating Conditions* is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) The input negative-voltage and output voltage ratings may be exceeded if the input and output current ratings are observed.
- (3) The value of V_{CC} is provided in the *Recommended Operating Conditions* table.

7.2 ESD Ratings

| PARAMETER | DEFINITION | VALUE | UNIT |
|-------------|--|-------|------|
| $V_{(ESD)}$ | Human body model (HBM), per ANSI/ESDA/JEDEC JS-001, all pins ⁽¹⁾ | 2000 | V |
| | Charged device model (CDM), per JEDEC specification JESD22-C101, all pins ⁽²⁾ | 1000 | |

(1) JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.

(2) JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process.

7.3 Recommended Operating Conditions

over operating free-air temperature range (unless otherwise noted)⁽¹⁾

| | | | MIN | MAX | UNIT |
|-----------------|------------------------------------|---|------------------------|-----------------|------|
| V _{CC} | Supply voltage | Operating | 1.65 | 5.5 | V |
| | | Data retention only | 1.5 | | |
| V _{IH} | High-level input voltage | V _{CC} = 1.65 V to 1.95 V | 0.65 × V _{CC} | | V |
| | | V _{CC} = 2.3 V to 2.7 V | 1.7 | | |
| | | V _{CC} = 3 V to 3.6 V | 2 | | |
| | | V _{CC} = 4.5 V to 5.5 V | 0.7 × V _{CC} | | |
| V _{IL} | Low-level input voltage | V _{CC} = 1.65 V to 1.95 V | 0.35 × V _{CC} | | V |
| | | V _{CC} = 2.3 V to 2.7 V | 0.7 | | |
| | | V _{CC} = 3 V to 3.6 V | 0.8 | | |
| | | V _{CC} = 4.5 V to 5.5 V | 0.3 × V _{CC} | | |
| V _I | Input voltage | | 0 | 5.5 | V |
| V _O | Output voltage | | 0 | V _{CC} | V |
| I _{OH} | High-level output current | V _{CC} = 1.65 V | –4 | | mA |
| | | V _{CC} = 2.3 V | –8 | | |
| | | V _{CC} = 3 V | –16 | | |
| | | V _{CC} = 4.5 V | –24 | | |
| I _{OL} | Low-level output current | V _{CC} = 1.65 V | 4 | | mA |
| | | V _{CC} = 2.3 V | 8 | | |
| | | V _{CC} = 3 V | 16 | | |
| | | V _{CC} = 4.5 V | 24 | | |
| Δt/Δv | Input transition rise or fall rate | V _{CC} = 1.8 V ± 0.15 V, 2.5 V ± 0.2 V | 20 | | ns/V |
| | | V _{CC} = 3.3 V ± 0.3 V | 10 | | |
| | | V _{CC} = 5 V ± 0.5 V | 5 | | |
| T _A | Operating free-air temperature | | –40 | 125 | °C |

(1) All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number [SCBA004](#).

7.4 Thermal Information

| THERMAL METRIC ⁽¹⁾ | SN74LVC1G126 | | | | | UNIT |
|---|--------------|--------|--------|--------|--------|------|
| | DBV | DCK | DRL | DRY | YZP | |
| | 5 PINS | 5 PINS | 5 PINS | 6 PINS | 5 PINS | |
| R _{θJA} Junction-to-ambient thermal resistance | 206 | 252 | 142 | 234 | 132 | °C/W |

(1) For more information about traditional and new thermal metrics, see the *IC Package Thermal Metrics* application report, [SPRA953](#).

7.5 Electrical Characteristics

over recommended operating free-air temperature range (unless otherwise noted)

| PARAMETER | TEST CONDITIONS | V _{CC} | −40°C to 85°C | | | −40°C to 125°C | | | UNIT | |
|------------------|---|--|-----------------------|--------------------|-----|-----------------------|--------------------|-----|------|--|
| | | | MIN | TYP ⁽¹⁾ | MAX | MIN | TYP ⁽¹⁾ | MAX | | |
| V _{OH} | I _{OH} = −100 µA | 1.65 V to 5.5 V | V _{CC} − 0.1 | | | V _{CC} − 0.1 | | | V | |
| | I _{OH} = −4 mA | 1.65 V | 1.2 | | | 1.2 | | | | |
| | I _{OH} = −8 mA | 2.3 V | 1.9 | | | 1.9 | | | | |
| | I _{OH} = −16 mA | 3 V | 2.4 | | | 2.4 | | | | |
| | I _{OH} = −24 mA | | 2.3 | | | 2.3 | | | | |
| | I _{OH} = −32 mA | 4.5 V | 3.8 | | | 3.8 | | | | |
| V _{OL} | I _{OL} = 100 µA | 1.65 V to 5.5 V | 0.1 | | | 0.1 | | | V | |
| | I _{OL} = 4 mA | 1.65 V | 0.45 | | | 0.45 | | | | |
| | I _{OL} = 8 mA | 2.3 V | 0.3 | | | 0.3 | | | | |
| | I _{OL} = 16 mA | 3 V | 0.4 | | | 0.4 | | | | |
| | I _{OL} = 24 mA | | 0.55 | | | 0.55 | | | | |
| | I _{OL} = 32 mA | 4.5 V | 0.55 | | | 0.55 | | | | |
| I _I | A or OE inputs | V _I = 5.5 V or GND | 0 to 5.5 V | | | ±5 | | | µA | |
| I _{off} | | V _I or V _O = 5.5 V | 0 | | | ±10 | | | µA | |
| I _{OZ} | | V _O = 0 to 5.5 V | 3.6 V | | | 10 | | | µA | |
| I _{CC} | V _I = 5.5 V or GND | I _O = 0 | 1.65 V to 5.5 V | | | 10 | | | µA | |
| ΔI _{CC} | One input at V _{CC} − 0.6 V, Other inputs at V _{CC} or GND | | 3 V to 5.5 V | | | 500 | | | µA | |
| C _I | | V _I = V _{CC} or GND | 3.3 V | | | 4 | | | pF | |

(1) All typical values are at V_{CC} = 3.3 V, T_A = 25°C.

7.6 Switching Characteristics, C_L = 15 pF

over recommended operating free-air temperature range, C_L = 15 pF (unless otherwise noted) (see [Figure 3](#))

| PARAMETER | FROM (INPUT) | TO (OUTPUT) | −40°C to 85°C | | | | | | | | UNIT | |
|-----------------|-----------------|----------------|-------------------------------------|-----|------------------------------------|-----|------------------------------------|-----|----------------------------------|-----|------|--|
| | | | V _{CC} = 1.8 V ± 0.15 V | | V _{CC} = 2.5 V ± 0.2 V | | V _{CC} = 3.3 V ± 0.3 V | | V _{CC} = 5 V ± 0.5 V | | | |
| | | | MIN | MAX | MIN | MAX | MIN | MAX | MIN | MAX | | |
| t _{pd} | A | Y | 1.7 | 6.9 | 0.6 | 4.6 | 0.6 | 3.7 | 0.5 | 3.4 | ns | |

7.7 Switching Characteristics, −40°C to 85°C

over recommended operating free-air temperature range, C_L = 30 pF or 50 pF (unless otherwise noted) (see [Figure 4](#))

| PARAMETER | FROM (INPUT) | TO (OUTPUT) | −40°C to 85°C | | | | | | | | UNIT | |
|------------------|-----------------|----------------|-------------------------------------|-----|------------------------------------|-----|------------------------------------|-----|----------------------------------|-----|------|--|
| | | | V _{CC} = 1.8 V ± 0.15 V | | V _{CC} = 2.5 V ± 0.2 V | | V _{CC} = 3.3 V ± 0.3 V | | V _{CC} = 5 V ± 0.5 V | | | |
| | | | MIN | MAX | MIN | MAX | MIN | MAX | MIN | MAX | | |
| t _{pd} | A | Y | 2.6 | 8 | 1.1 | 5.5 | 1 | 4.5 | 1 | 4 | ns | |
| t _{en} | OE | Y | 2.8 | 9.4 | 1.3 | 6.6 | 1.2 | 5.3 | 1 | 5 | ns | |
| t _{dis} | OE | Y | 1.6 | 9.8 | 1 | 5.5 | 1 | 5.5 | 1 | 4.2 | ns | |

7.8 Switching Characteristics, -40°C to 125°C

over recommended operating free-air temperature range, $C_L = 30 \text{ pF}$ or 50 pF (unless otherwise noted) (see [Figure 4](#))

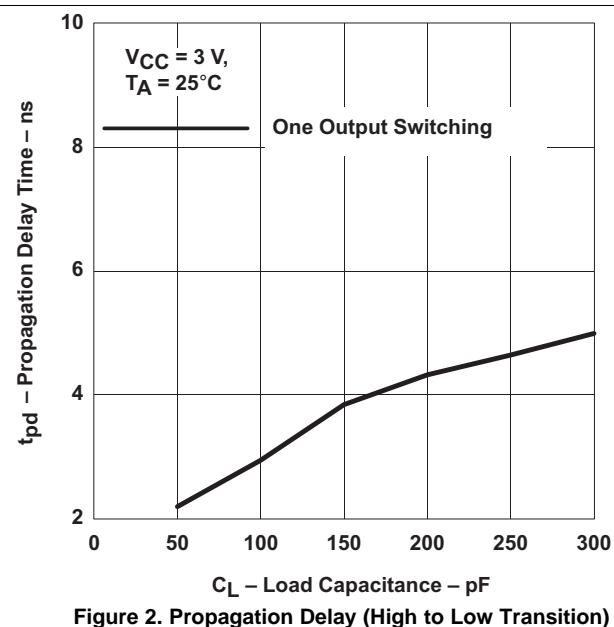
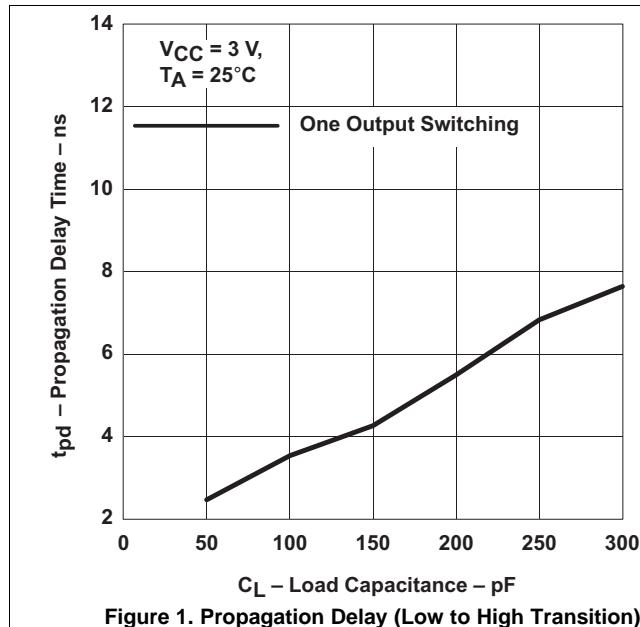
| PARAMETER | FROM (INPUT) | TO (OUTPUT) | -40°C to 125°C | | | | | | UNIT | |
|-----------|-----------------|----------------|--|-----|---|-----|---|-----|---|-----|
| | | | $V_{CC} = 1.8 \text{ V}$ $\pm 0.15 \text{ V}$ | | $V_{CC} = 2.5 \text{ V}$ $\pm 0.2 \text{ V}$ | | $V_{CC} = 3.3 \text{ V}$ $\pm 0.3 \text{ V}$ | | $V_{CC} = 5 \text{ V}$ $\pm 0.5 \text{ V}$ | |
| | | | MIN | MAX | MIN | MAX | MIN | MAX | MIN | MAX |
| t_{pd} | A | Y | 2.6 | 9 | 1.1 | 5.7 | 1 | 4.7 | 1 | 4.2 |
| t_{en} | OE | Y | 2.8 | 9.6 | 1.3 | 6.8 | 1.2 | 5.5 | 1 | 5.2 |
| t_{dis} | OE | Y | 1.6 | 10 | 1 | 5.7 | 1 | 5.7 | 1 | 4.4 |

7.9 Operating Characteristics

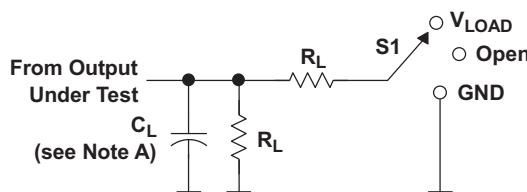
$T_A = 25^{\circ}\text{C}$

| PARAMETER | TEST CONDITIONS | $V_{CC} = 1.8 \text{ V}$ | $V_{CC} = 2.5 \text{ V}$ | $V_{CC} = 3.3 \text{ V}$ | $V_{CC} = 5 \text{ V}$ | UNIT |
|--|----------------------|--------------------------|--------------------------|--------------------------|------------------------|------|
| | | TYP | TYP | TYP | TYP | |
| | $f = 10 \text{ MHz}$ | | | | | |
| C_{pd} Power dissipation capacitance | Outputs enabled | 19 | 19 | 19 | 21 | pF |
| | Outputs disabled | 2 | 2 | 3 | 4 | |

7.10 Typical Characteristics



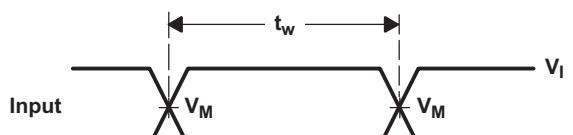
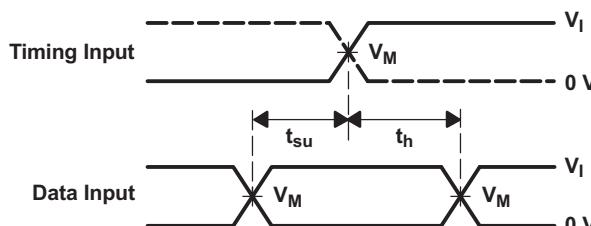
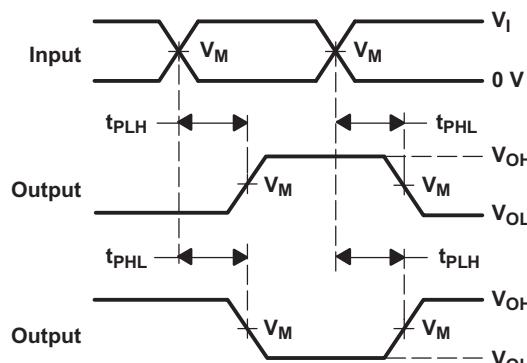
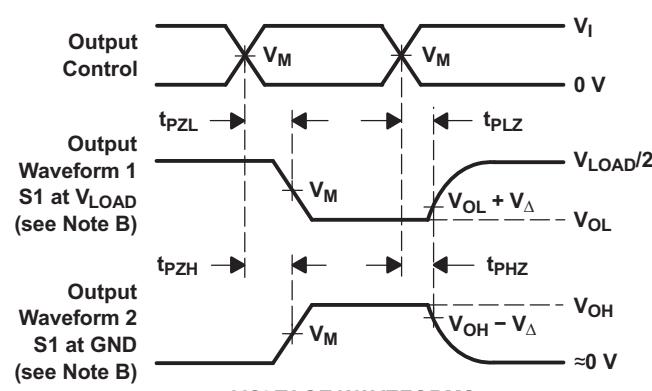
8 Parameter Measurement Information



| TEST | S_1 |
|-------------------|------------|
| t_{PLH}/t_{PHL} | Open |
| t_{PZL}/t_{PZL} | V_{LOAD} |
| t_{PHZ}/t_{PZH} | GND |

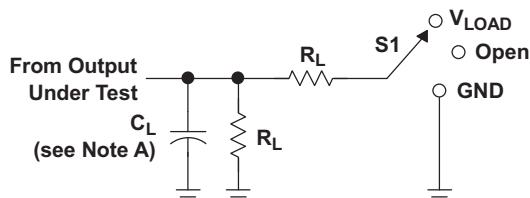
LOAD CIRCUIT

| V_{CC} | INPUTS | | V_M | V_{LOAD} | C_L | R_L | V_Δ |
|----------------------------------|----------|----------------------|------------|-------------------|-------|--------------|------------|
| | V_I | t_r/t_f | | | | | |
| $1.8\text{ V} \pm 0.15\text{ V}$ | V_{CC} | $\leq 2\text{ ns}$ | $V_{CC}/2$ | $2 \times V_{CC}$ | 15 pF | 1 M Ω | 0.15 V |
| $2.5\text{ V} \pm 0.2\text{ V}$ | V_{CC} | $\leq 2\text{ ns}$ | $V_{CC}/2$ | $2 \times V_{CC}$ | 15 pF | 1 M Ω | 0.15 V |
| $3.3\text{ V} \pm 0.3\text{ V}$ | 3 V | $\leq 2.5\text{ ns}$ | 1.5 V | 6 V | 15 pF | 1 M Ω | 0.3 V |
| $5\text{ V} \pm 0.5\text{ V}$ | V_{CC} | $\leq 2.5\text{ ns}$ | $V_{CC}/2$ | $2 \times V_{CC}$ | 15 pF | 1 M Ω | 0.3 V |

VOLTAGE WAVEFORMS
PULSE DURATIONVOLTAGE WAVEFORMS
SETUP AND HOLD TIMESVOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES
INVERTING AND NONINVERTING OUTPUTSVOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES
LOW- AND HIGH-LEVEL ENABLING

NOTES: A. C_L includes probe and jig capacitance.
 B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
 C. All input pulses are supplied by generators having the following characteristics: PRR $\leq 10\text{ MHz}$, $Z_O = 50\text{ }\Omega$.
 D. The outputs are measured one at a time, with one transition per measurement.
 E. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
 F. t_{PZL} and t_{PZH} are the same as t_{en} .
 G. t_{PLH} and t_{PHL} are the same as t_{pd} .
 H. All parameters and waveforms are not applicable to all devices.

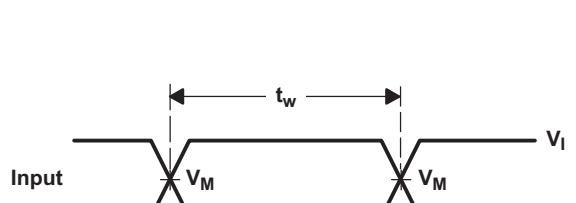
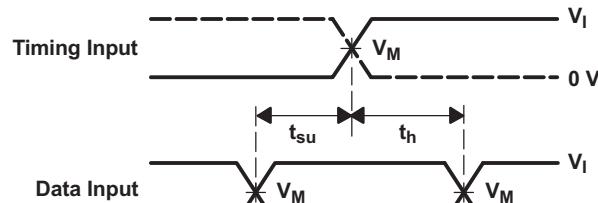
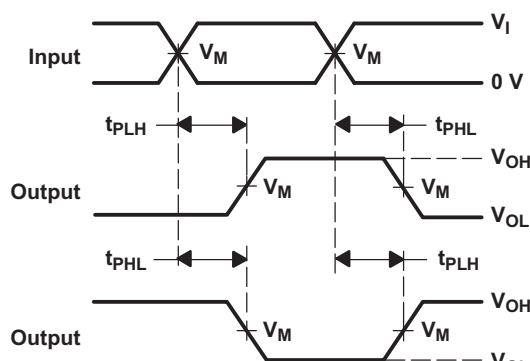
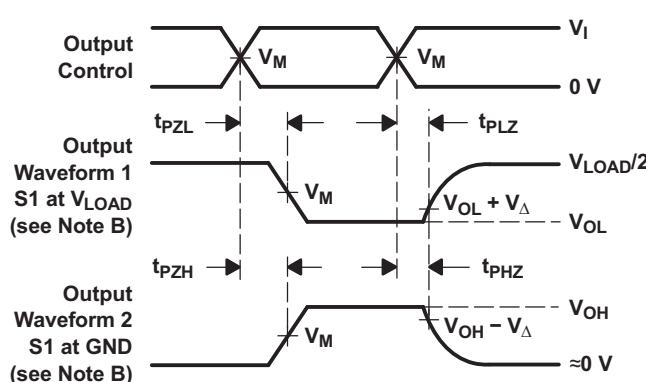
Figure 3. Load Circuit and Voltage Waveforms

Parameter Measurement Information (continued)


| TEST | S_1 |
|-------------------|------------|
| t_{PLH}/t_{PHL} | Open |
| t_{PLZ}/t_{PZL} | V_{LOAD} |
| t_{PHZ}/t_{PZH} | GND |

LOAD CIRCUIT

| V_{CC} | INPUTS | | V_M | V_{LOAD} | C_L | R_L | V_Δ |
|------------------------------------|----------|-----------------------|------------|-------------------|-------|--------------|------------|
| | V_I | t_r/t_f | | | | | |
| $1.8 \text{ V} \pm 0.15 \text{ V}$ | V_{CC} | $\leq 2 \text{ ns}$ | $V_{CC}/2$ | $2 \times V_{CC}$ | 30 pF | 1 k Ω | 0.15 V |
| $2.5 \text{ V} \pm 0.2 \text{ V}$ | V_{CC} | $\leq 2 \text{ ns}$ | $V_{CC}/2$ | $2 \times V_{CC}$ | 30 pF | 500 Ω | 0.15 V |
| $3.3 \text{ V} \pm 0.3 \text{ V}$ | 3 V | $\leq 2.5 \text{ ns}$ | 1.5 V | 6 V | 50 pF | 500 Ω | 0.3 V |
| $5 \text{ V} \pm 0.5 \text{ V}$ | V_{CC} | $\leq 2.5 \text{ ns}$ | $V_{CC}/2$ | $2 \times V_{CC}$ | 50 pF | 500 Ω | 0.3 V |


**VOLTAGE WAVEFORMS
PULSE DURATION**

**VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES**

**VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES
INVERTING AND NONINVERTING OUTPUTS**

**VOLTAGE WAVEFORMS
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LOW- AND HIGH-LEVEL ENABLING**

NOTES: A. C_L includes probe and jig capacitance.

B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.

C. All input pulses are supplied by generators having the following characteristics: PRR $\leq 10 \text{ MHz}$, $Z_O = 50 \Omega$.

D. The outputs are measured one at a time, with one transition per measurement.

E. t_{PLZ} and t_{PHZ} are the same as t_{dis} .

F. t_{PZL} and t_{PZH} are the same as t_{en} .

G. t_{PLH} and t_{PHL} are the same as t_{pd} .

H. All parameters and waveforms are not applicable to all devices.

Figure 4. Load Circuit and Voltage Waveforms

9 Detailed Description

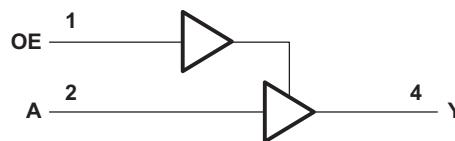
9.1 Overview

The SN74LVC1G126 device contains a dual buffer gate with output enable control and performs the Boolean function $Y = A$.

This device is fully specified for partial-power-down applications using I_{off} . The I_{off} circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down.

To ensure the high-impedance state during power up or power down, OE should be tied to GND through a pull-down resistor; the minimum value of the resistor is determined by the current-sourcing capability of the driver.

9.2 Functional Block Diagram



9.3 Feature Description

- 1.65 V to 5.5 V operating voltage range
- Allows down voltage translation
 - 5 V to 3.3 V
 - 5 V or 3.3 V to 1.8 V
- Inputs accept voltages to 5.5 V
 - 5.5-V tolerance on input pin when $V_{CC} = 0$ V
- I_{off} feature
 - Allows voltage on the inputs and outputs when V_{CC} is 0 V
 - Able to reduce leakage when V_{CC} is 0 V

9.4 Device Functional Modes

Table 1. Function Table

| INPUTS | | OUTPUT Y |
|--------|---|-------------|
| OE | A | |
| H | H | H |
| H | L | L |
| L | X | Z |

10 Application and Implementation

NOTE

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes. Customers should validate and test their design implementation to confirm system functionality.

10.1 Application Information

The SN74LVC1G126 device is a high-drive CMOS device that can be used as an output enabled buffer with a high output drive, such as an LED application. It can produce 24 mA of drive current at 3.3 V, making it ideal for driving multiple outputs and good for high speed applications up to 100 MHz. The inputs are 5.5-V tolerant allowing it to translate down to V_{CC} .

10.2 Typical Application

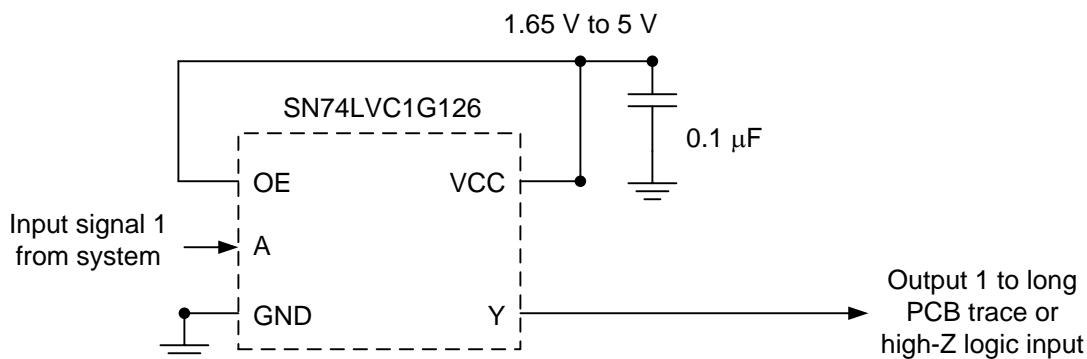


Figure 5. Application Schematic

10.2.1 Design Requirements

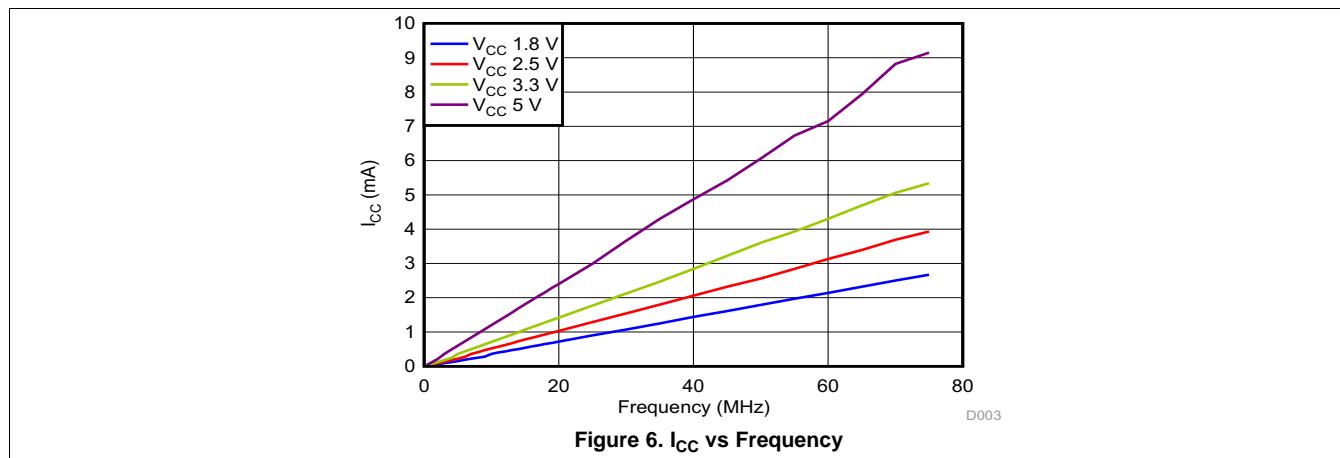
This device uses CMOS technology and has balanced output drive. Care should be taken to avoid bus contention because it can drive currents that would exceed maximum limits. Outputs can be combined to produce higher drive but the high drive will also create faster edges into light loads, so routing and load conditions should be considered to prevent ringing.

10.2.2 Detailed Design Procedure

1. Recommended Input Conditions:
 - For rise time and fall time specifications, see $\Delta t/\Delta V$ in the [Recommended Operating Conditions](#) table.
 - For specified high and low levels, see V_{IH} and V_{IL} in the [Recommended Operating Conditions](#) table.
 - Inputs are overvoltage tolerant allowing them to go as high as 5.5 V at any valid V_{CC} .
2. Recommend Output Conditions:
 - Load currents should not exceed 50 mA per output and 100 mA total for the part.

Typical Application (continued)

10.2.3 Application Curves



11 Power Supply Recommendations

The power supply can be any voltage between the MIN and MAX supply voltage rating located in the *Recommended Operating Conditions* table.

Each V_{CC} terminal should have a good bypass capacitor to prevent power disturbance. For devices with a single supply, a 0.1- μF capacitor is recommended. If there are multiple V_{CC} terminals, then 0.01- μF or 0.022- μF capacitors are recommended for each power terminal. It is ok to parallel multiple bypass capacitors to reject different frequencies of noise. Multiple bypass capacitors may be paralleled to reject different frequencies of noise. The bypass capacitor should be installed as close to the power terminal as possible for the best results.

12 Layout

12.1 Layout Guidelines

When using multiple bit logic devices, inputs should not float. In many cases, functions or parts of functions of digital logic devices are unused. Some examples are when only two inputs of a triple-input AND gate are used, or when only 3 of the 4-buffer gates are used. Such input pins should not be left unconnected because the undefined voltages at the outside connections result in undefined operational states.

Specified in [Figure 7](#) are rules that must be observed under all circumstances. All unused inputs of digital logic devices must be connected to a high or low bias to prevent them from floating. The logic level that should be applied to any particular unused input depends on the function of the device. Generally they will be tied to GND or V_{CC} , whichever makes more sense or is more convenient. It is acceptable to float outputs unless the part is a transceiver. If the transceiver has an output enable pin, it will disable the outputs section of the part when asserted. This will not disable the input section of the I/Os so they also cannot float when disabled.

12.2 Layout Example

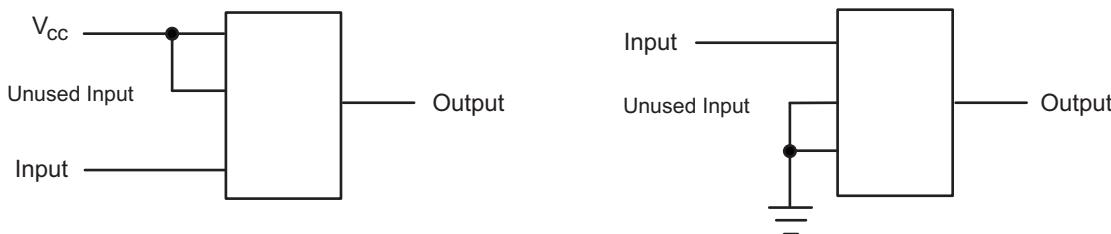


Figure 7. Layout Diagram

13 Device and Documentation Support

13.1 Trademarks

NanoFree is a trademark of Texas Instruments.
All other trademarks are the property of their respective owners.

13.2 Electrostatic Discharge Caution

 These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

13.3 Glossary

[SLYZ022](#) — *TI Glossary*.

This glossary lists and explains terms, acronyms and definitions.

14 Mechanical, Packaging, and Orderable Information

The following pages include mechanical packaging and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser based versions of this data sheet, refer to the left hand navigation.

PACKAGING INFORMATION

| Orderable Device | Status (1) | Package Type | Package Drawing | Pins | Package Qty | Eco Plan (2) | Lead finish/ Ball material (6) | MSL Peak Temp (3) | Op Temp (°C) | Device Marking (4/5) | Samples |
|------------------|---------------|--------------|-----------------|------|-------------|-----------------|--------------------------------------|----------------------|--------------|--------------------------------------|---------|
| 74LVC1G126DBVRE4 | ACTIVE | SOT-23 | DBV | 5 | 3000 | RoHS & Green | NIPDAU | Level-1-260C-UNLIM | -40 to 125 | C26F | Samples |
| 74LVC1G126DBVRG4 | ACTIVE | SOT-23 | DBV | 5 | 3000 | RoHS & Green | NIPDAU | Level-1-260C-UNLIM | -40 to 125 | C26F | Samples |
| 74LVC1G126DBVTE4 | ACTIVE | SOT-23 | DBV | 5 | 250 | RoHS & Green | NIPDAU | Level-1-260C-UNLIM | -40 to 125 | C26F | Samples |
| 74LVC1G126DBVTG4 | ACTIVE | SOT-23 | DBV | 5 | 250 | RoHS & Green | NIPDAU | Level-1-260C-UNLIM | -40 to 125 | C26F | Samples |
| 74LVC1G126DCKRE4 | ACTIVE | SC70 | DCK | 5 | 3000 | RoHS & Green | NIPDAU | Level-1-260C-UNLIM | -40 to 125 | CN5 | Samples |
| 74LVC1G126DCKRG4 | ACTIVE | SC70 | DCK | 5 | 3000 | RoHS & Green | NIPDAU | Level-1-260C-UNLIM | -40 to 125 | CN5 | Samples |
| 74LVC1G126DCKTG4 | ACTIVE | SC70 | DCK | 5 | 250 | RoHS & Green | NIPDAU | Level-1-260C-UNLIM | -40 to 125 | CN5 | Samples |
| 74LVC1G126DRLRG4 | ACTIVE | SOT-5X3 | DRL | 5 | 4000 | TBD | Call TI | Call TI | -40 to 125 | | Samples |
| SN74LVC1G126DBVR | ACTIVE | SOT-23 | DBV | 5 | 3000 | RoHS & Green | NIPDAU SN | Level-1-260C-UNLIM | -40 to 125 | (C265, C26F, C26J, C26K, C26R, C26T) | Samples |
| SN74LVC1G126DBVT | ACTIVE | SOT-23 | DBV | 5 | 250 | RoHS & Green | NIPDAU SN | Level-1-260C-UNLIM | -40 to 125 | (C265, C26F, C26J, C26K, C26R) | Samples |
| SN74LVC1G126DCKR | ACTIVE | SC70 | DCK | 5 | 3000 | RoHS & Green | NIPDAU SN | Level-1-260C-UNLIM | -40 to 125 | (CN5, CNF, CNJ, CNK, CNR, CNT) | Samples |
| SN74LVC1G126DCKT | ACTIVE | SC70 | DCK | 5 | 250 | RoHS & Green | NIPDAU SN | Level-1-260C-UNLIM | -40 to 125 | (CN5, CNF, CNJ, CNK, CNR) | Samples |
| SN74LVC1G126DRLR | ACTIVE | SOT-5X3 | DRL | 5 | 4000 | RoHS & Green | NIPDAUAG | Level-1-260C-UNLIM | -40 to 125 | (CN7, CNR) | Samples |
| SN74LVC1G126DRYR | ACTIVE | SON | DRY | 6 | 5000 | RoHS & Green | NIPDAU | Level-1-260C-UNLIM | -40 to 125 | CN | Samples |
| SN74LVC1G126DSFR | ACTIVE | SON | DSF | 6 | 5000 | RoHS & Green | NIPDAU | Level-1-260C-UNLIM | -40 to 125 | CN | Samples |
| SN74LVC1G126YZPR | ACTIVE | DSBGA | YZP | 5 | 3000 | RoHS & Green | SNAGCU | Level-1-260C-UNLIM | -40 to 85 | (CN7, CNN) | Samples |

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) Marking: There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Device Markings: Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead finish/Ball material: Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

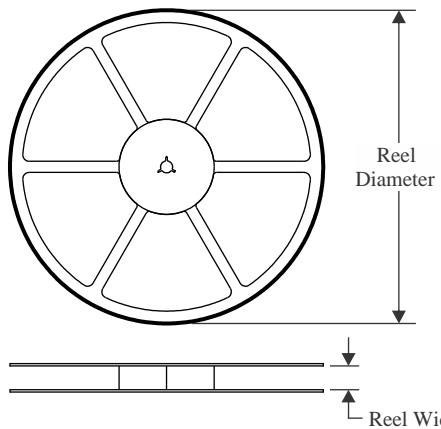
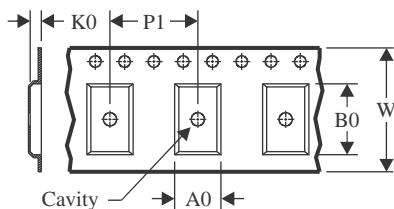
In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

OTHER QUALIFIED VERSIONS OF SN74LVC1G126 :

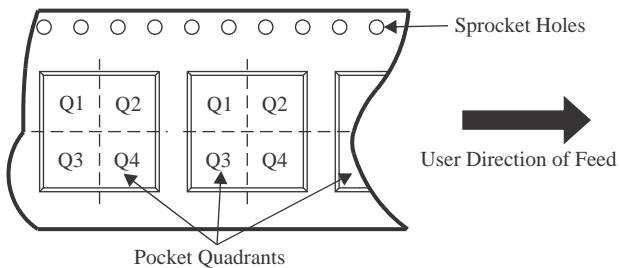
- Automotive : [SN74LVC1G126-Q1](#)
- Enhanced Product : [SN74LVC1G126-EP](#)

NOTE: Qualified Version Definitions:

- Automotive - Q100 devices qualified for high-reliability automotive applications targeting zero defects
- Enhanced Product - Supports Defense, Aerospace and Medical Applications

TAPE AND REEL INFORMATION
REEL DIMENSIONS

TAPE DIMENSIONS


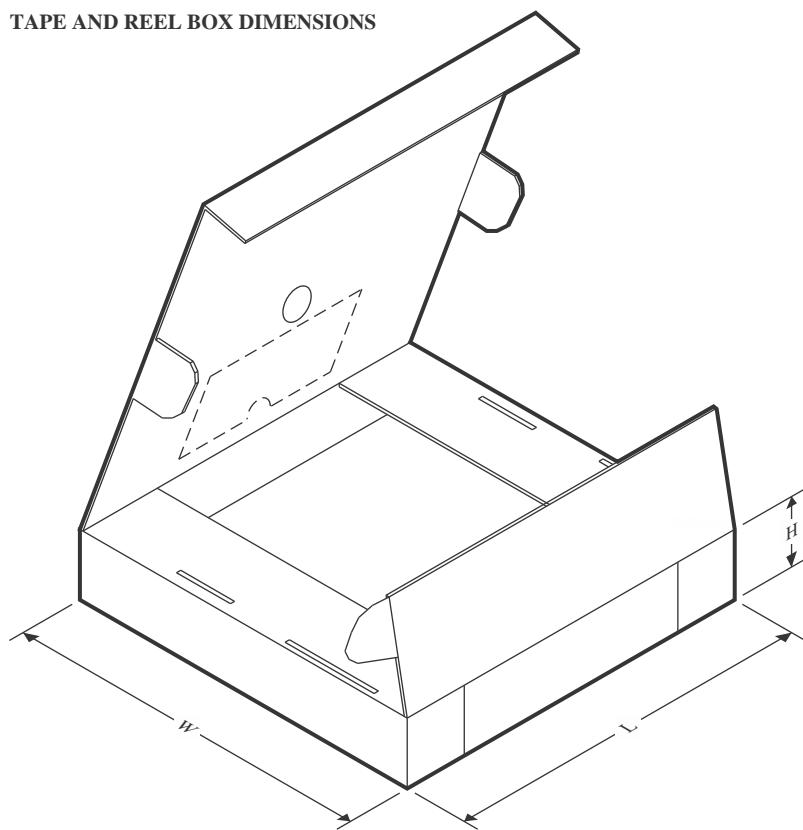
| | |
|----|---|
| A0 | Dimension designed to accommodate the component width |
| B0 | Dimension designed to accommodate the component length |
| K0 | Dimension designed to accommodate the component thickness |
| W | Overall width of the carrier tape |
| P1 | Pitch between successive cavity centers |

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE


*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Reel Diameter (mm) | Reel Width W1 (mm) | A0 (mm) | B0 (mm) | K0 (mm) | P1 (mm) | W (mm) | Pin1 Quadrant |
|------------------|--------------|-----------------|------|------|--------------------|--------------------|---------|---------|---------|---------|--------|---------------|
| 74LVC1G126DBVRG4 | SOT-23 | DBV | 5 | 3000 | 178.0 | 9.0 | 3.23 | 3.17 | 1.37 | 4.0 | 8.0 | Q3 |
| 74LVC1G126DBVTG4 | SOT-23 | DBV | 5 | 250 | 178.0 | 9.0 | 3.23 | 3.17 | 1.37 | 4.0 | 8.0 | Q3 |
| 74LVC1G126DCKRG4 | SC70 | DCK | 5 | 3000 | 178.0 | 9.2 | 2.4 | 2.4 | 1.22 | 4.0 | 8.0 | Q3 |
| 74LVC1G126DCKTG4 | SC70 | DCK | 5 | 250 | 178.0 | 9.2 | 2.4 | 2.4 | 1.22 | 4.0 | 8.0 | Q3 |
| SN74LVC1G126DBVR | SOT-23 | DBV | 5 | 3000 | 178.0 | 9.0 | 3.3 | 3.2 | 1.4 | 4.0 | 8.0 | Q3 |
| SN74LVC1G126DBVR | SOT-23 | DBV | 5 | 3000 | 178.0 | 9.0 | 3.23 | 3.17 | 1.37 | 4.0 | 8.0 | Q3 |
| SN74LVC1G126DBVR | SOT-23 | DBV | 5 | 3000 | 178.0 | 9.2 | 3.3 | 3.23 | 1.55 | 4.0 | 8.0 | Q3 |
| SN74LVC1G126DBVT | SOT-23 | DBV | 5 | 250 | 180.0 | 8.4 | 3.23 | 3.17 | 1.37 | 4.0 | 8.0 | Q3 |
| SN74LVC1G126DBVT | SOT-23 | DBV | 5 | 250 | 178.0 | 9.0 | 3.3 | 3.2 | 1.4 | 4.0 | 8.0 | Q3 |
| SN74LVC1G126DBVT | SOT-23 | DBV | 5 | 250 | 178.0 | 9.2 | 3.3 | 3.23 | 1.55 | 4.0 | 8.0 | Q3 |
| SN74LVC1G126DBVT | SOT-23 | DBV | 5 | 250 | 178.0 | 9.0 | 3.23 | 3.17 | 1.37 | 4.0 | 8.0 | Q3 |
| SN74LVC1G126DCKR | SC70 | DCK | 5 | 3000 | 178.0 | 9.2 | 2.4 | 2.4 | 1.22 | 4.0 | 8.0 | Q3 |
| SN74LVC1G126DCKR | SC70 | DCK | 5 | 3000 | 180.0 | 8.4 | 2.47 | 2.3 | 1.25 | 4.0 | 8.0 | Q3 |
| SN74LVC1G126DCKT | SC70 | DCK | 5 | 250 | 180.0 | 8.4 | 2.47 | 2.3 | 1.25 | 4.0 | 8.0 | Q3 |
| SN74LVC1G126DCKT | SC70 | DCK | 5 | 250 | 178.0 | 9.2 | 2.4 | 2.4 | 1.22 | 4.0 | 8.0 | Q3 |
| SN74LVC1G126DCKT | SC70 | DCK | 5 | 250 | 178.0 | 9.0 | 2.4 | 2.5 | 1.2 | 4.0 | 8.0 | Q3 |

| Device | Package Type | Package Drawing | Pins | SPQ | Reel Diameter (mm) | Reel Width W1 (mm) | A0 (mm) | B0 (mm) | K0 (mm) | P1 (mm) | W (mm) | Pin1 Quadrant |
|------------------|--------------|-----------------|------|------|--------------------|--------------------|---------|---------|---------|---------|--------|---------------|
| SN74LVC1G126DRLR | SOT-5X3 | DRL | 5 | 4000 | 180.0 | 8.4 | 1.98 | 1.78 | 0.69 | 4.0 | 8.0 | Q3 |
| SN74LVC1G126DRYR | SON | DRY | 6 | 5000 | 180.0 | 8.4 | 1.2 | 1.65 | 0.69 | 4.0 | 8.0 | Q1 |
| SN74LVC1G126DSFR | SON | DSF | 6 | 5000 | 180.0 | 9.5 | 1.16 | 1.16 | 0.5 | 4.0 | 8.0 | Q2 |
| SN74LVC1G126YZPR | DSBGA | YZP | 5 | 3000 | 178.0 | 9.2 | 1.02 | 1.52 | 0.63 | 4.0 | 8.0 | Q1 |

TAPE AND REEL BOX DIMENSIONS


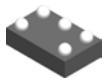
*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Length (mm) | Width (mm) | Height (mm) |
|------------------|--------------|-----------------|------|------|-------------|------------|-------------|
| 74LVC1G126DBVRG4 | SOT-23 | DBV | 5 | 3000 | 180.0 | 180.0 | 18.0 |
| 74LVC1G126DBVTG4 | SOT-23 | DBV | 5 | 250 | 180.0 | 180.0 | 18.0 |
| 74LVC1G126DCKRG4 | SC70 | DCK | 5 | 3000 | 180.0 | 180.0 | 18.0 |
| 74LVC1G126DCKTG4 | SC70 | DCK | 5 | 250 | 180.0 | 180.0 | 18.0 |
| SN74LVC1G126DBVR | SOT-23 | DBV | 5 | 3000 | 180.0 | 180.0 | 18.0 |
| SN74LVC1G126DBVR | SOT-23 | DBV | 5 | 3000 | 180.0 | 180.0 | 18.0 |
| SN74LVC1G126DBVR | SOT-23 | DBV | 5 | 3000 | 180.0 | 180.0 | 18.0 |
| SN74LVC1G126DBVT | SOT-23 | DBV | 5 | 250 | 202.0 | 201.0 | 28.0 |
| SN74LVC1G126DBVT | SOT-23 | DBV | 5 | 250 | 180.0 | 180.0 | 18.0 |
| SN74LVC1G126DBVT | SOT-23 | DBV | 5 | 250 | 180.0 | 180.0 | 18.0 |
| SN74LVC1G126DBVT | SOT-23 | DBV | 5 | 250 | 180.0 | 180.0 | 18.0 |
| SN74LVC1G126DCKR | SC70 | DCK | 5 | 3000 | 180.0 | 180.0 | 18.0 |
| SN74LVC1G126DCKR | SC70 | DCK | 5 | 3000 | 202.0 | 201.0 | 28.0 |
| SN74LVC1G126DCKT | SC70 | DCK | 5 | 250 | 202.0 | 201.0 | 28.0 |
| SN74LVC1G126DCKT | SC70 | DCK | 5 | 250 | 180.0 | 180.0 | 18.0 |
| SN74LVC1G126DCKT | SC70 | DCK | 5 | 250 | 180.0 | 180.0 | 18.0 |
| SN74LVC1G126DRLR | SOT-5X3 | DRL | 5 | 4000 | 202.0 | 201.0 | 28.0 |
| SN74LVC1G126DRYR | SON | DRY | 6 | 5000 | 200.0 | 183.0 | 25.0 |

| Device | Package Type | Package Drawing | Pins | SPQ | Length (mm) | Width (mm) | Height (mm) |
|------------------|--------------|-----------------|------|------|-------------|------------|-------------|
| SN74LVC1G126DSFR | SON | DSF | 6 | 5000 | 184.0 | 184.0 | 19.0 |
| SN74LVC1G126YZPR | DSBGA | YZP | 5 | 3000 | 220.0 | 220.0 | 35.0 |

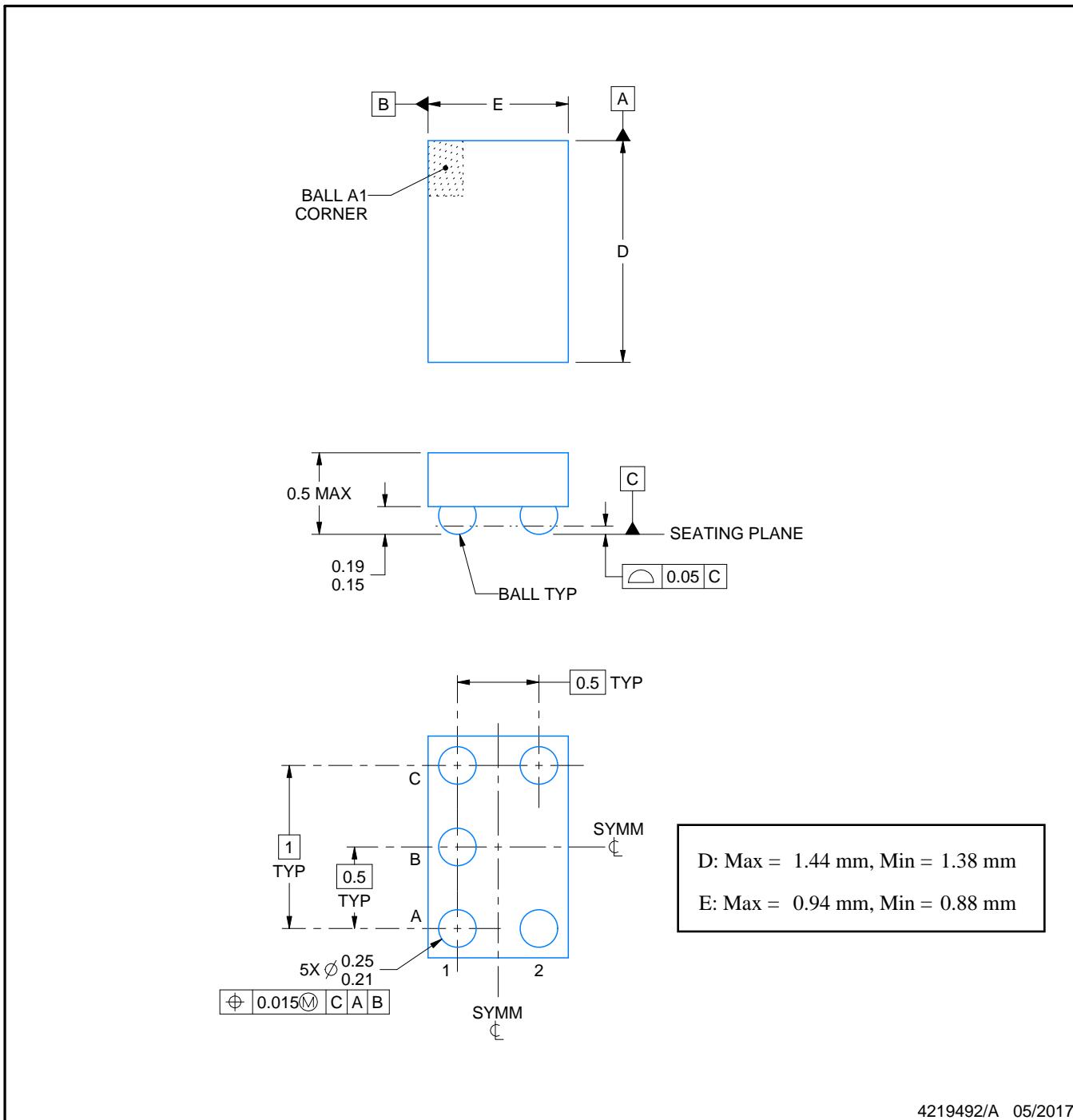
PACKAGE OUTLINE

YZP0005



DSBGA - 0.5 mm max height

DIE SIZE BALL GRID ARRAY



4219492/A 05/2017

NOTES:

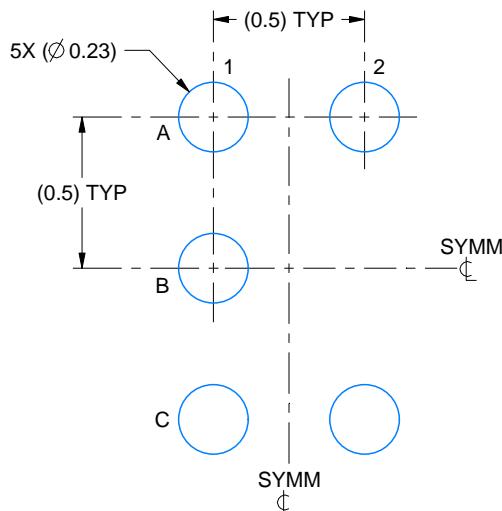
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.

EXAMPLE BOARD LAYOUT

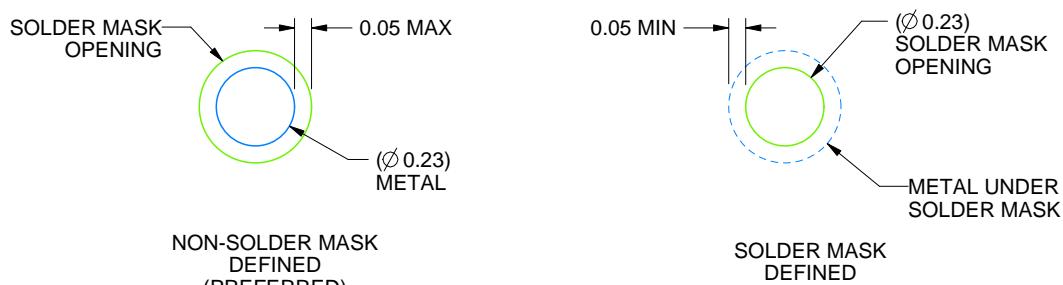
YZP0005

DSBGA - 0.5 mm max height

DIE SIZE BALL GRID ARRAY



LAND PATTERN EXAMPLE
SCALE:40X



SOLDER MASK DETAILS
NOT TO SCALE

4219492/A 05/2017

NOTES: (continued)

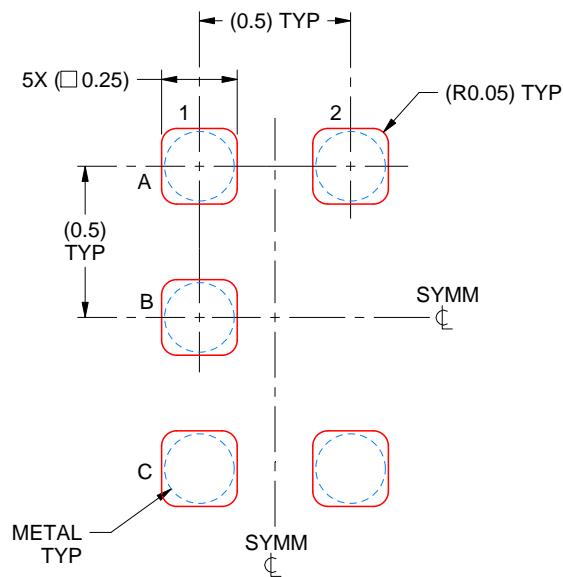
3. Final dimensions may vary due to manufacturing tolerance considerations and also routing constraints. For more information, see Texas Instruments literature number SNVA009 (www.ti.com/lit/snva009).

EXAMPLE STENCIL DESIGN

YZP0005

DSBGA - 0.5 mm max height

DIE SIZE BALL GRID ARRAY



SOLDER PASTE EXAMPLE
BASED ON 0.1 mm THICK STENCIL
SCALE:40X

4219492/A 05/2017

NOTES: (continued)

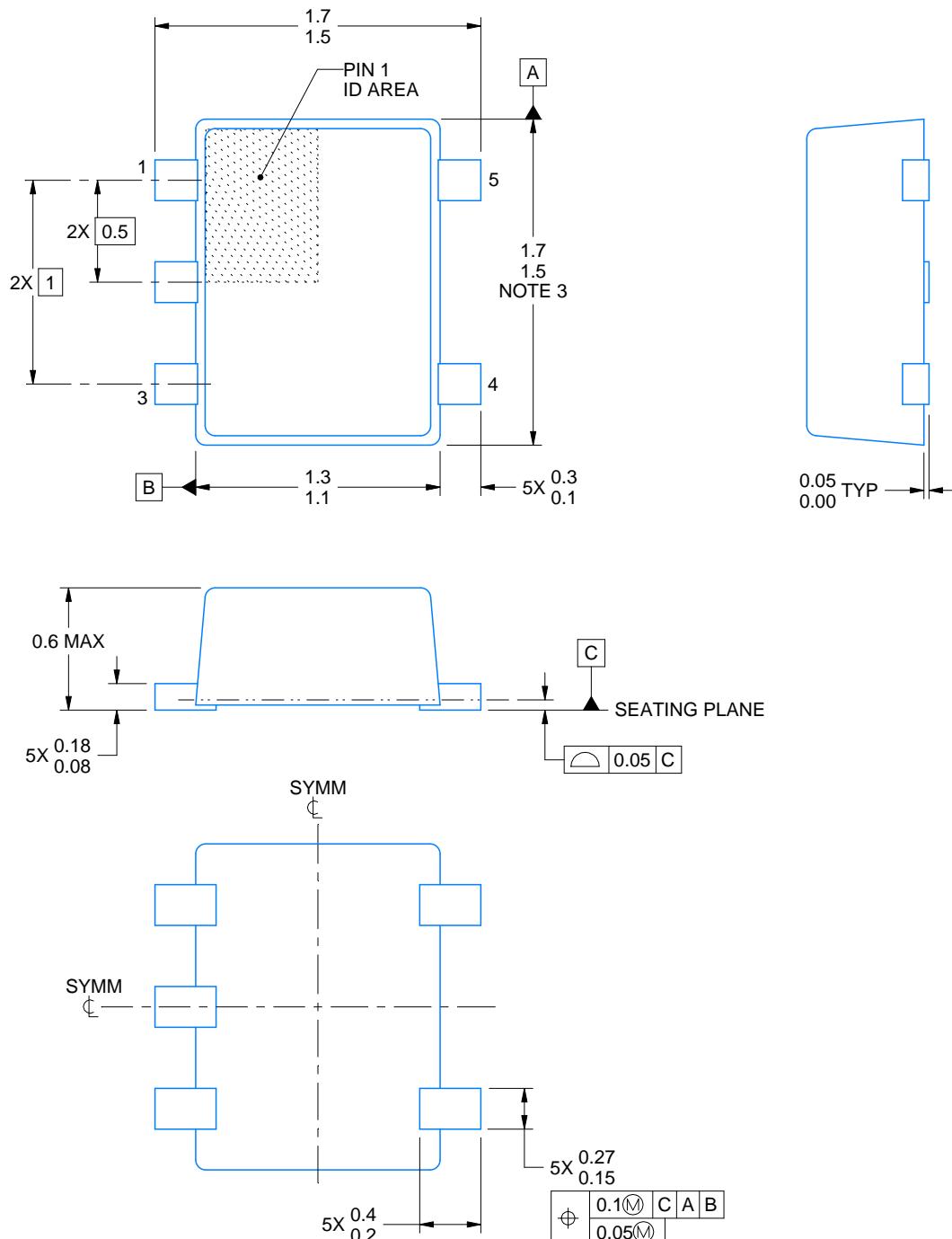
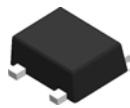
4. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release.

PACKAGE OUTLINE

SOT - 0.6 mm max height

PLASTIC SMALL OUTLINE

DRL0005A



4220753/B 12/2020

NOTES:

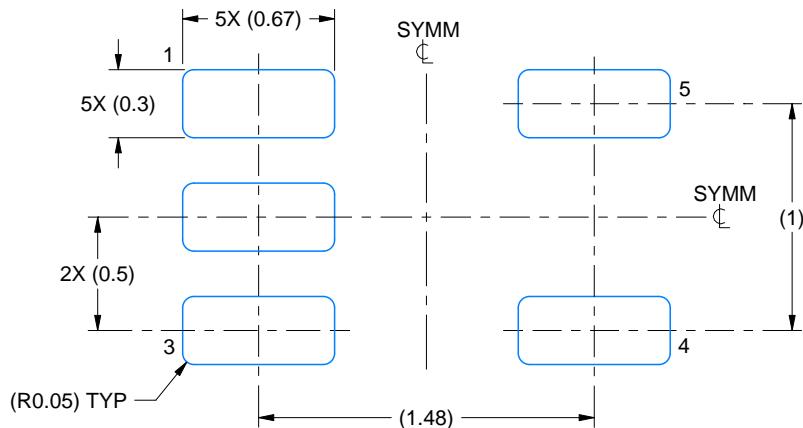
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. Reference JEDEC registration MO-293 Variation UAAD-1

EXAMPLE BOARD LAYOUT

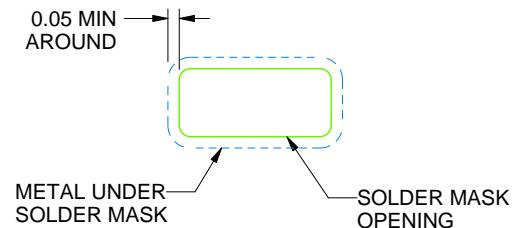
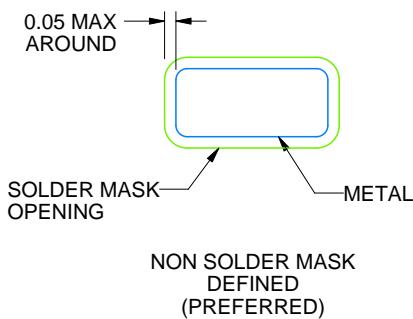
DRL0005A

SOT - 0.6 mm max height

PLASTIC SMALL OUTLINE



LAND PATTERN EXAMPLE
SCALE:30X



SOLDERMASK DETAILS

4220753/B 12/2020

NOTES: (continued)

5. Publication IPC-7351 may have alternate designs.

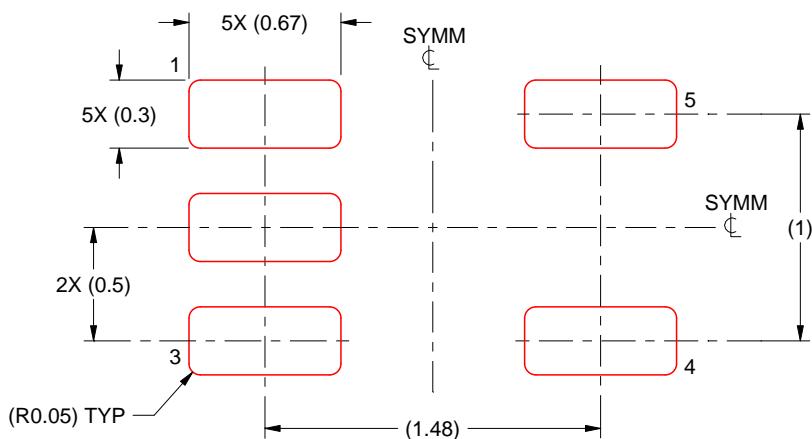
6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

DRL0005A

SOT - 0.6 mm max height

PLASTIC SMALL OUTLINE



SOLDER PASTE EXAMPLE
BASED ON 0.1 mm THICK STENCIL
SCALE:30X

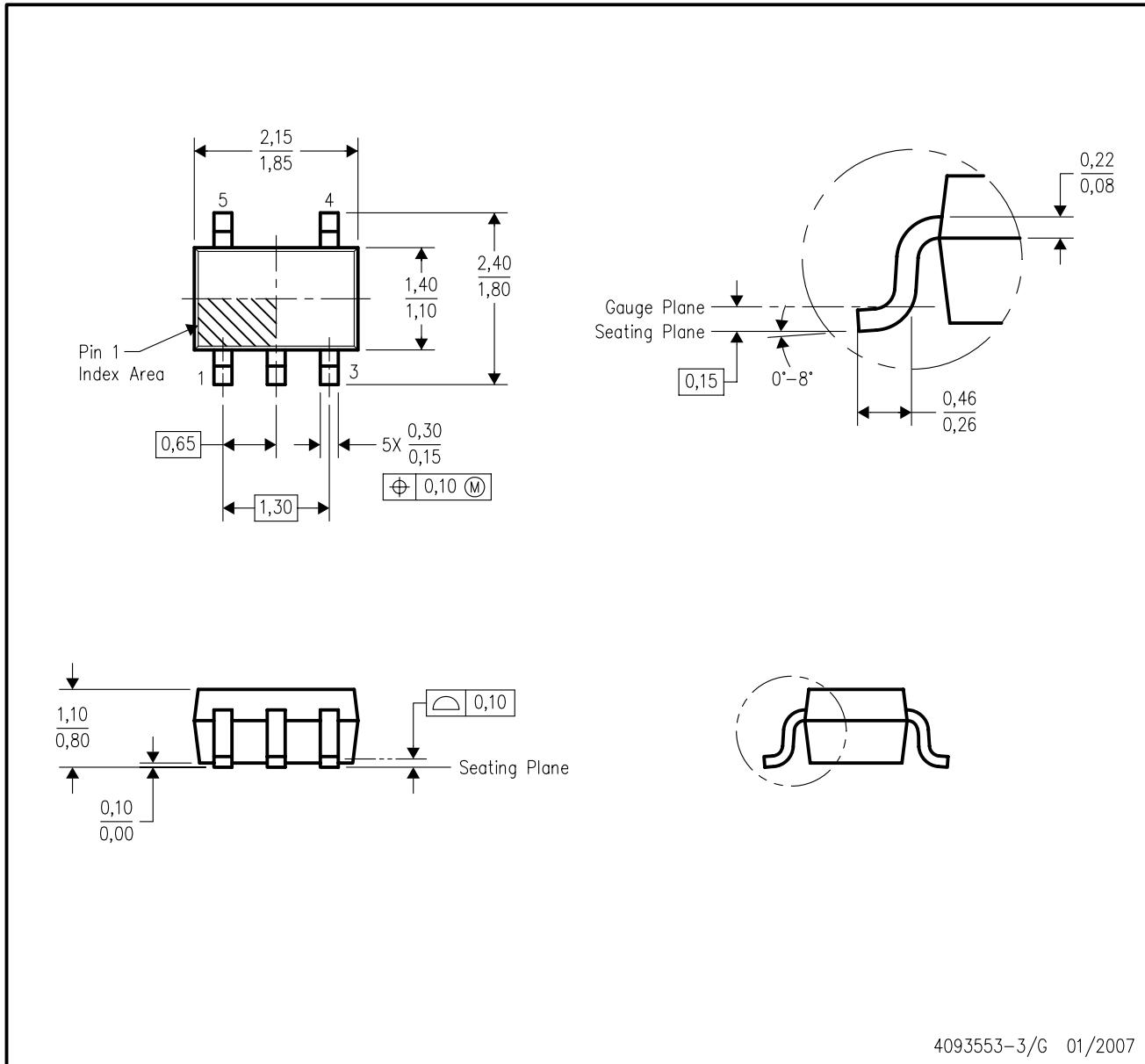
4220753/B 12/2020

NOTES: (continued)

7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
8. Board assembly site may have different recommendations for stencil design.

DCK (R-PDSO-G5)

PLASTIC SMALL-OUTLINE PACKAGE



4093553-3/G 01/2007

NOTES:

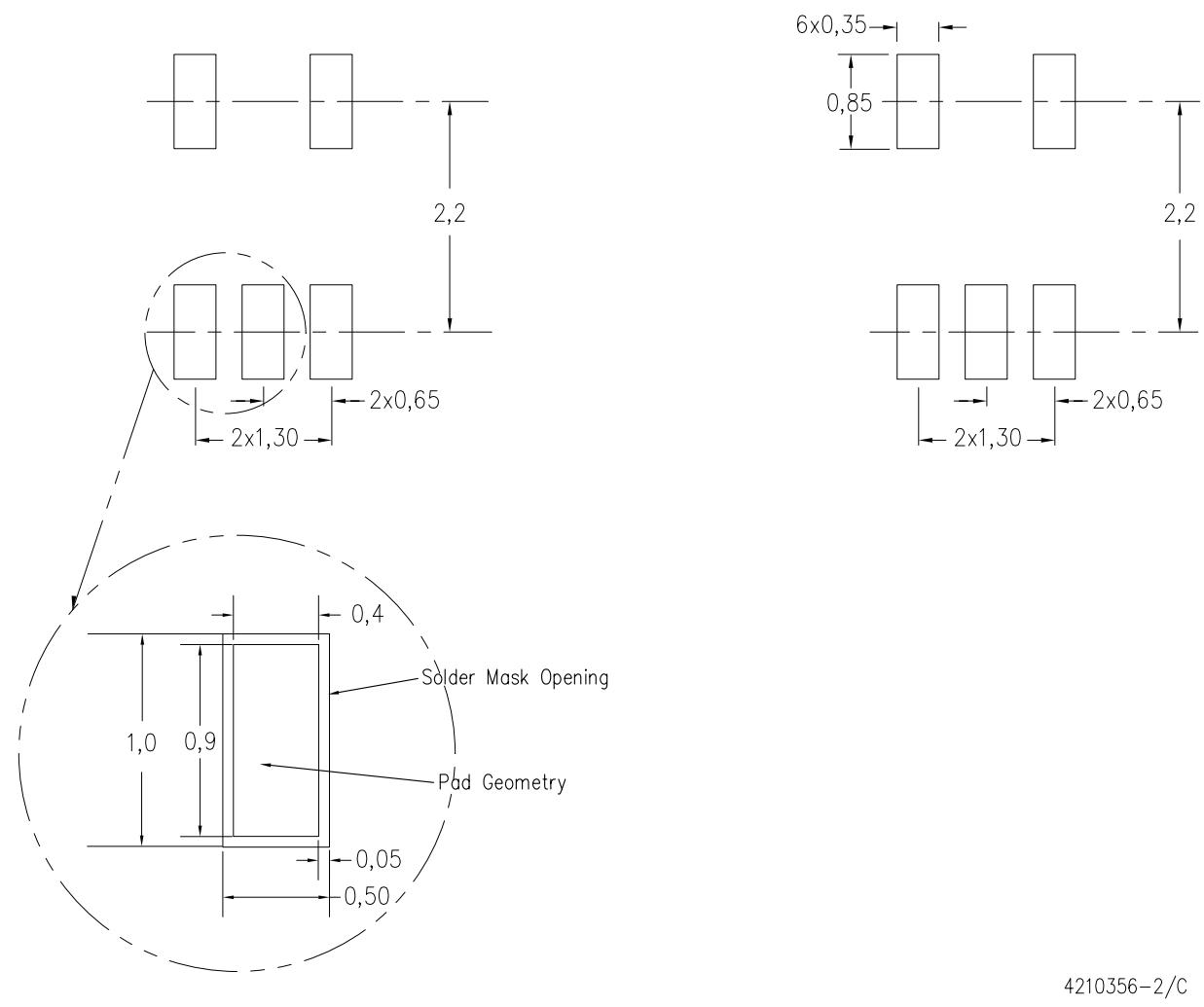
- All linear dimensions are in millimeters.
- This drawing is subject to change without notice.
- Body dimensions do not include mold flash or protrusion. Mold flash and protrusion shall not exceed 0.15 per side.
- Falls within JEDEC MO-203 variation AA.

DCK (R-PDSO-G5)

PLASTIC SMALL OUTLINE

Example Board Layout

Stencil Openings
Based on a stencil thickness
of .127mm (.005inch).



NOTES:

- All linear dimensions are in millimeters.
- This drawing is subject to change without notice.
- Customers should place a note on the circuit board fabrication drawing not to alter the center solder mask defined pad.
- Publication IPC-7351 is recommended for alternate designs.
- Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Example stencil design based on a 50% volumetric metal load solder paste. Refer to IPC-7525 for other stencil recommendations.

DRY 6

GENERIC PACKAGE VIEW

USON - 0.6 mm max height

PLASTIC SMALL OUTLINE - NO LEAD

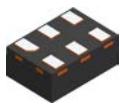


Images above are just a representation of the package family, actual package may vary.
Refer to the product data sheet for package details.

4207181/G

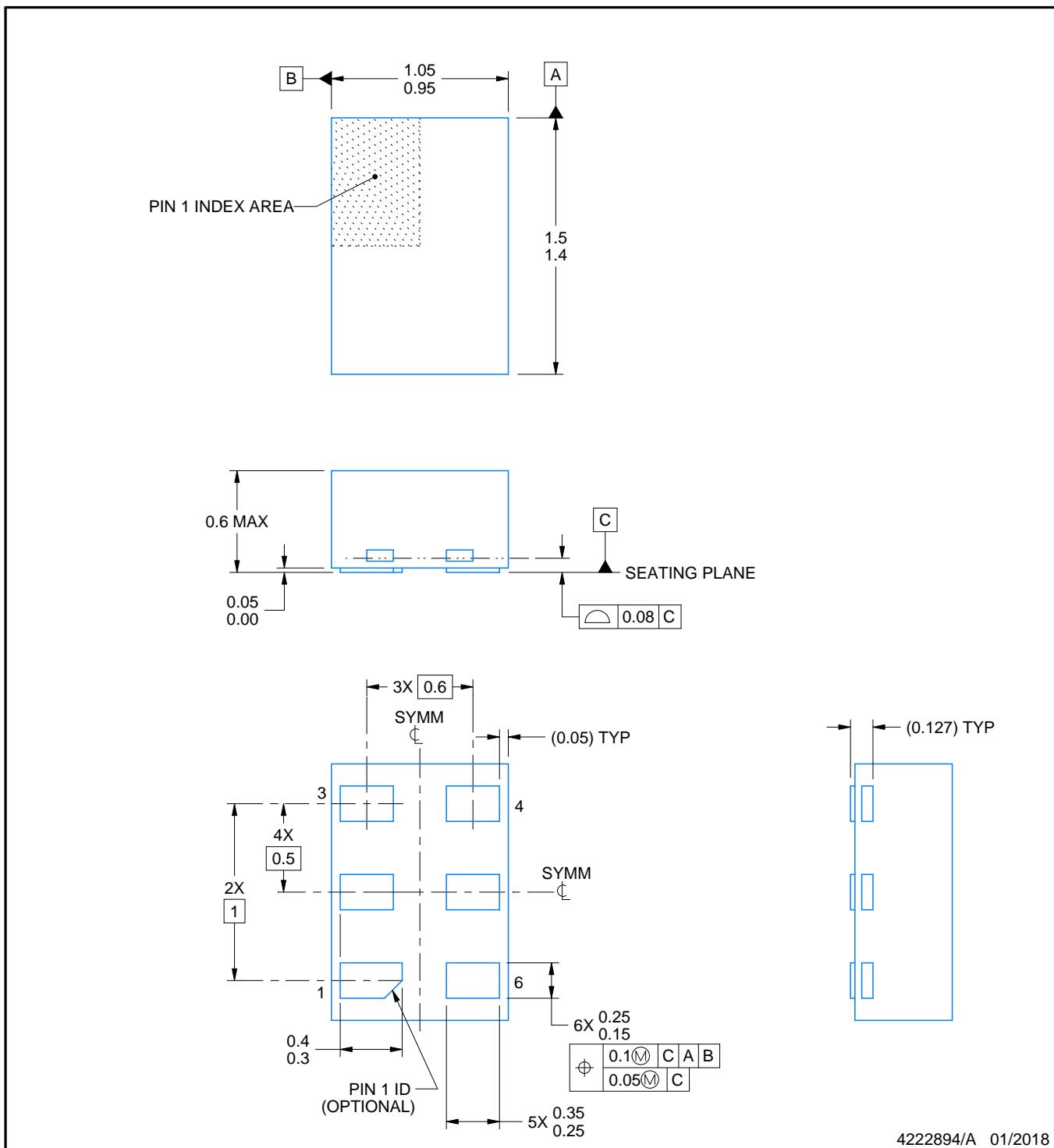
PACKAGE OUTLINE

DRY0006A



USON - 0.6 mm max height

PLASTIC SMALL OUTLINE - NO LEAD



NOTES:

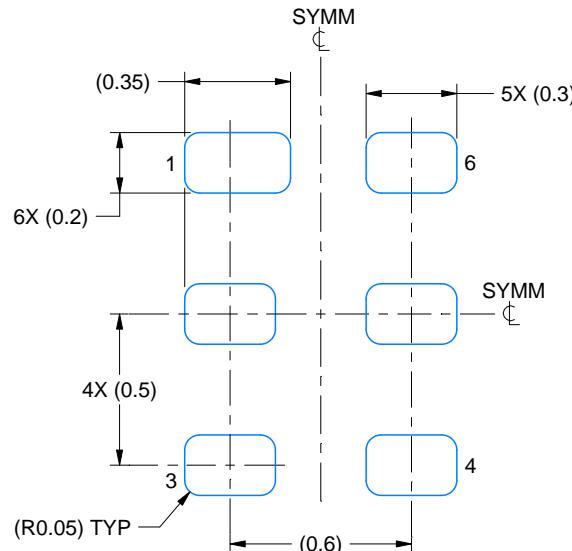
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.

EXAMPLE BOARD LAYOUT

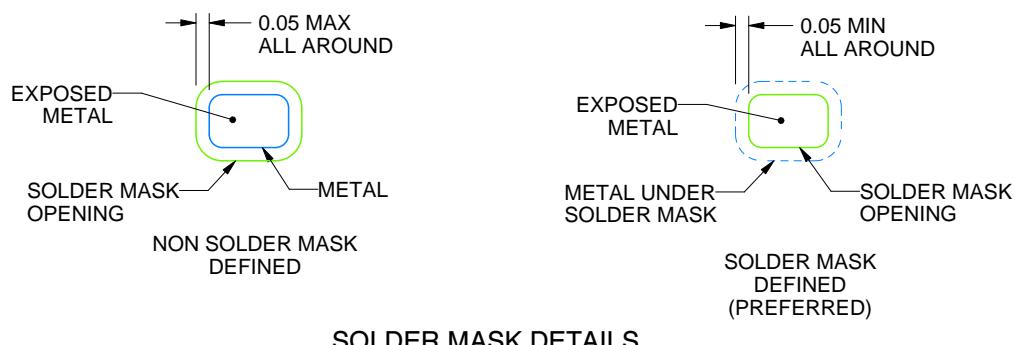
DRY0006A

USON - 0.6 mm max height

PLASTIC SMALL OUTLINE - NO LEAD



LAND PATTERN EXAMPLE
1:1 RATIO WITH PKG SOLDER PADS
EXPOSED METAL SHOWN
SCALE:40X



SOLDER MASK DETAILS

4222894/A 01/2018

NOTES: (continued)

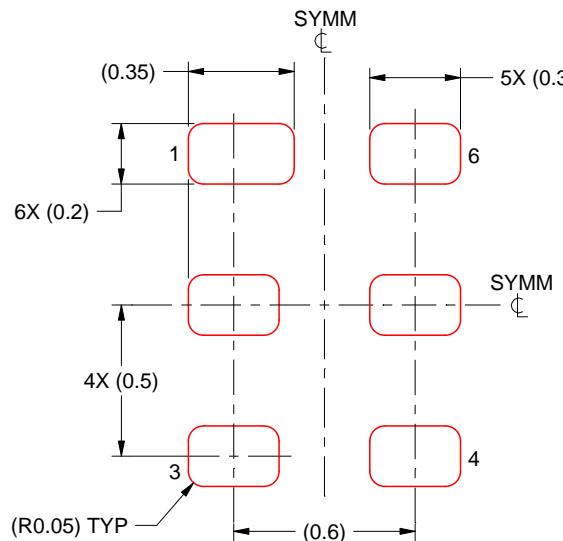
3. For more information, see QFN/SON PCB application report in literature No. SLUA271 (www.ti.com/lit/slua271).

EXAMPLE STENCIL DESIGN

DRY0006A

USON - 0.6 mm max height

PLASTIC SMALL OUTLINE - NO LEAD



SOLDER PASTE EXAMPLE
BASED ON 0.075 - 0.1 mm THICK STENCIL
SCALE:40X

4222894/A 01/2018

NOTES: (continued)

4. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

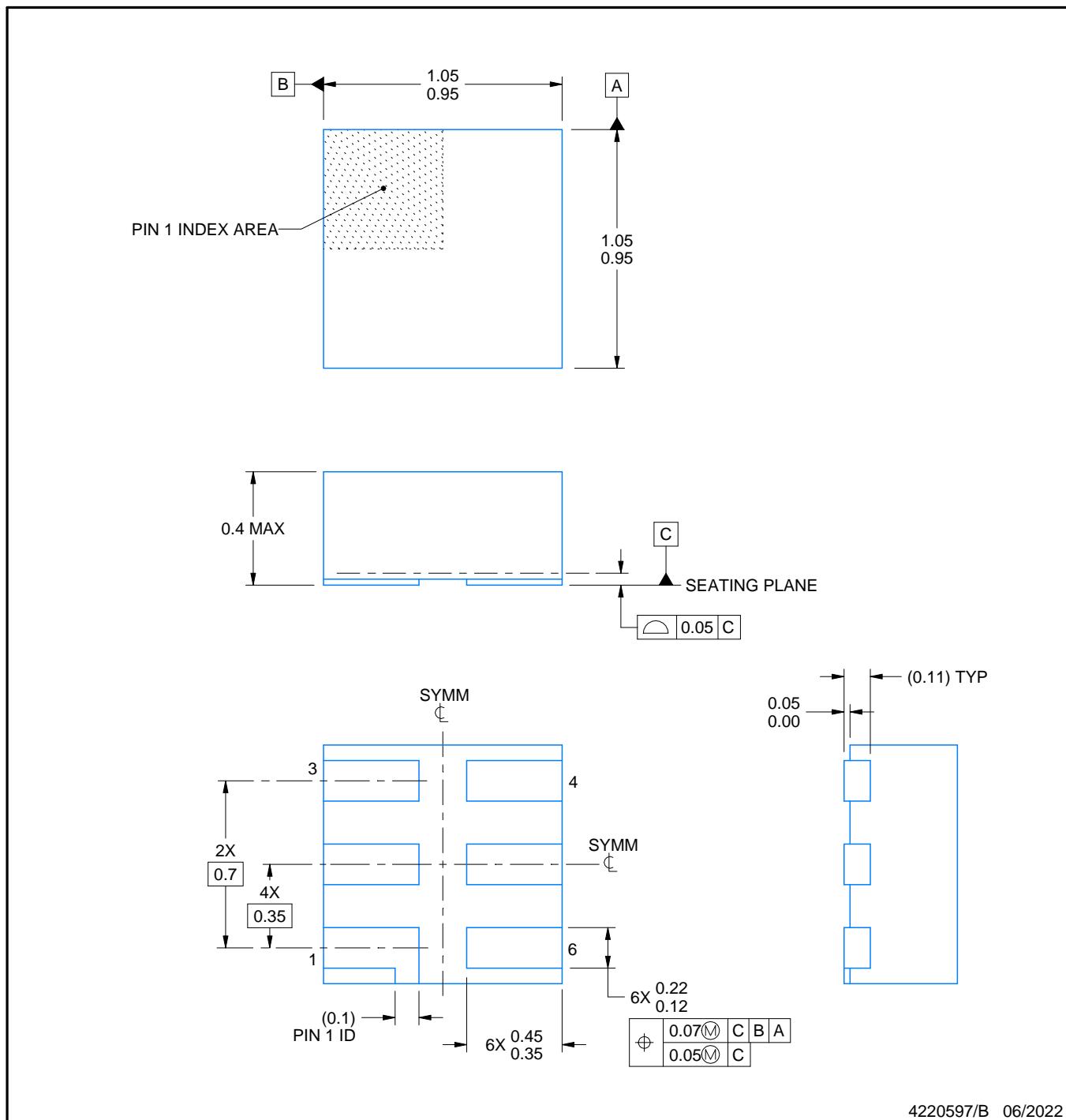


PACKAGE OUTLINE

DSF0006A

X2SON - 0.4 mm max height

PLASTIC SMALL OUTLINE - NO LEAD



4220597/B 06/2022

NOTES:

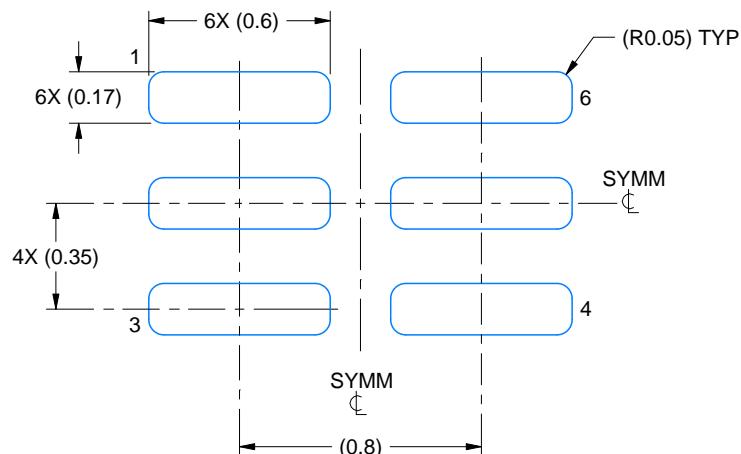
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. Reference JEDEC registration MO-287, variation X2AAF.

EXAMPLE BOARD LAYOUT

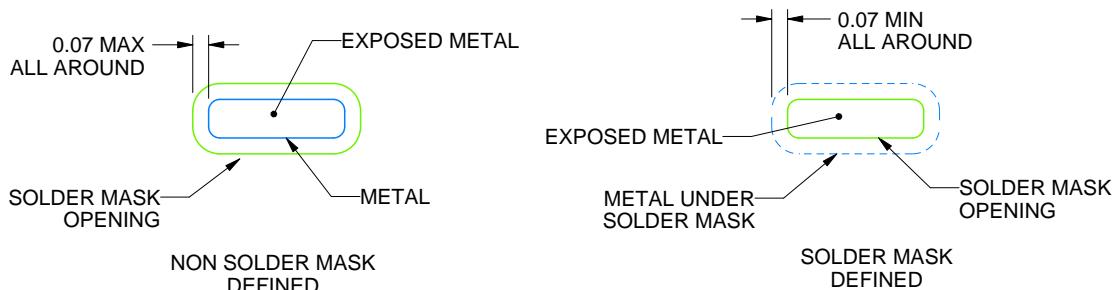
DSF0006A

X2SON - 0.4 mm max height

PLASTIC SMALL OUTLINE - NO LEAD



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE:40X



SOLDER MASK DETAILS

4220597/B 06/2022

NOTES: (continued)

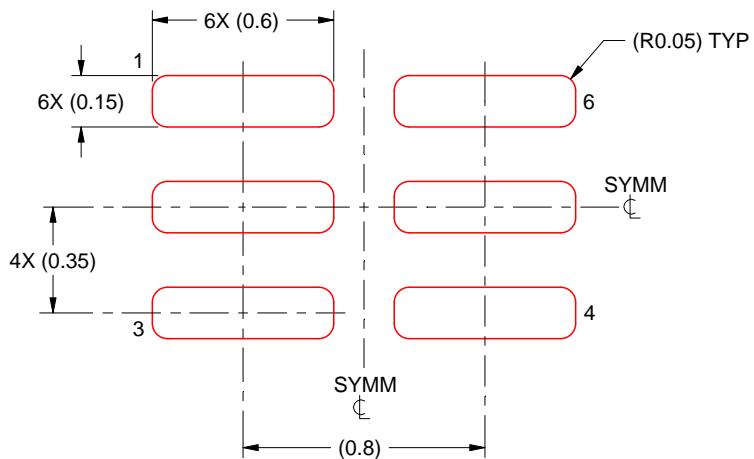
4. For more information, see Texas Instruments literature number SLUA271 (www.ti.com/lit/slua271).

EXAMPLE STENCIL DESIGN

DSF0006A

X2SON - 0.4 mm max height

PLASTIC SMALL OUTLINE - NO LEAD



SOLDER PASTE EXAMPLE
BASED ON 0.09 mm THICK STENCIL

PRINTED SOLDER COVERAGE BY AREA UNDER PACKAGE
SCALE:40X

4220597/B 06/2022

4. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

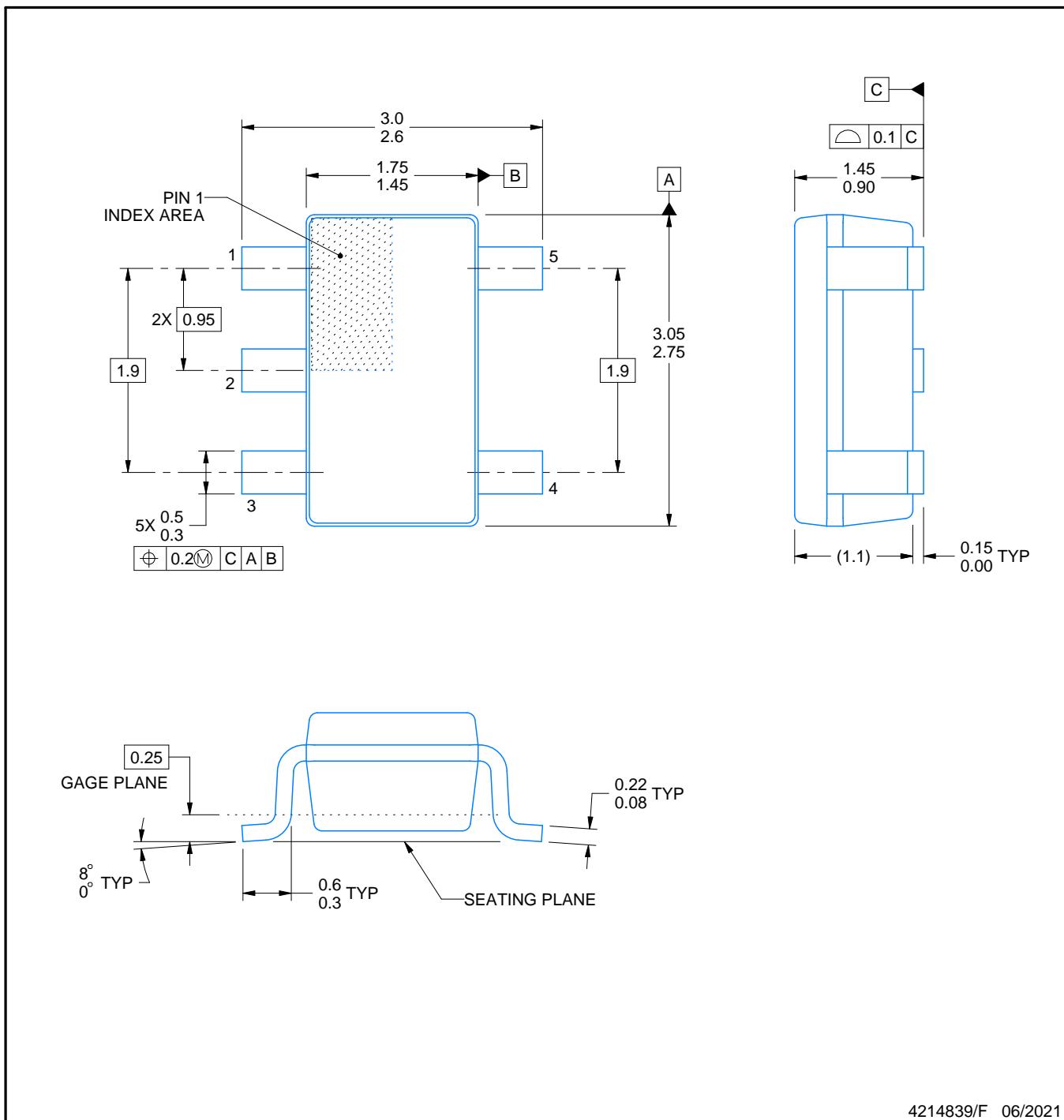
PACKAGE OUTLINE

DBV0005A



SOT-23 - 1.45 mm max height

SMALL OUTLINE TRANSISTOR



NOTES:

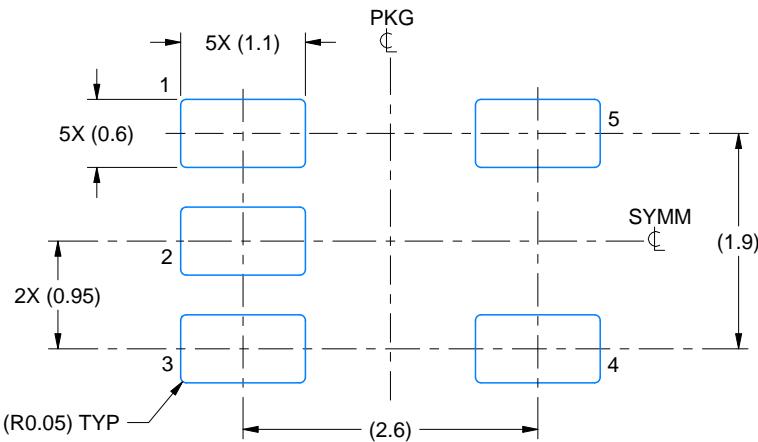
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. Reference JEDEC MO-178.
4. Body dimensions do not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.25 mm per side.

EXAMPLE BOARD LAYOUT

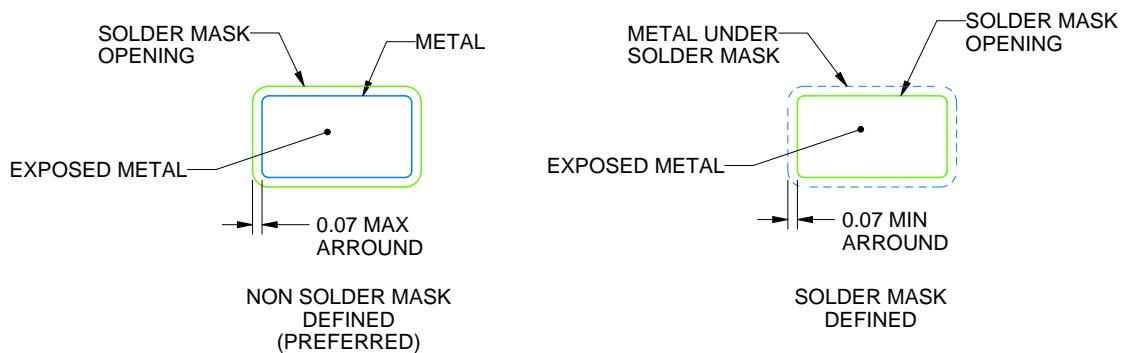
DBV0005A

SOT-23 - 1.45 mm max height

SMALL OUTLINE TRANSISTOR



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE:15X



SOLDER MASK DETAILS

4214839/F 06/2021

NOTES: (continued)

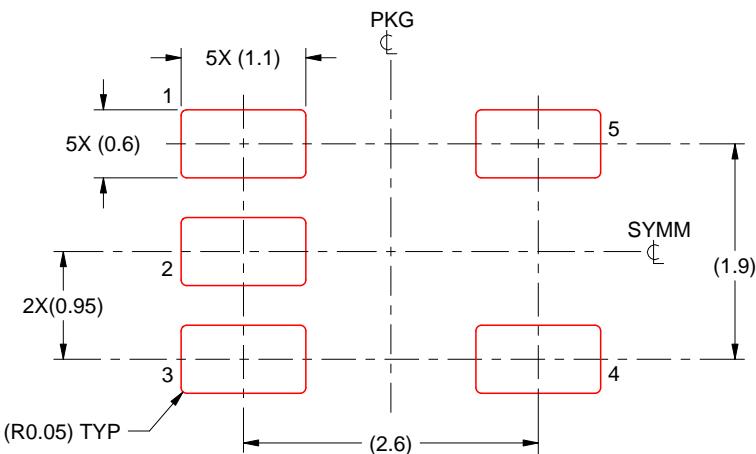
5. Publication IPC-7351 may have alternate designs.
6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

DBV0005A

SOT-23 - 1.45 mm max height

SMALL OUTLINE TRANSISTOR



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE:15X

4214839/F 06/2021

NOTES: (continued)

7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
8. Board assembly site may have different recommendations for stencil design.

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